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Attorney Docket no: SEL 189

11/02/00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)

TAKAYAMA et al.)

Serial No.: 09/598,736)

Filed: June 21, 2000)

For: Wiring Material, Semiconductor
Device Provided With A Wiring
Using The Wiring Material And
Method Of Manufacturing
Thereof)

Examiner:)

Art Unit:)

I hereby certify that this correspondence is being
deposited with the United States Postal Service as
first class mail in an envelope addressed to:
the Assistant Commissioner for Patents, Washington,
D.C. 20231 on July 27, 2000
(Date of Deposit)

Christine Muilenburg
Name of applicant, assignee, or Registered Rep.
Christine Muilenburg 7-27-2000
Signature Date

July 27, 2000

Assistant Commissioner for Patents
Washington D.C. 20231

PRELIMINARY AMENDMENT A

Prior to examination, please enter the following amendment in the above-identified
application:

IN THE DRAWINGS:

Please amend the enclosed drawings as shown in red.

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REMARKS

This amendment is being submitted to correct the drawings as filed.

In particular, in Fig. 30 as filed, the graph had a typographical error that showed "resistivity"
v. sputtering power. The label "resistivity" was erroneous put on the graph. It should have been
"stress". This is supported by the specification. For example, page 8, lns. 10-11 state "Fig. 30 is a
graph showing the relationship between sputtering power and stress" (emphasis added). See also